



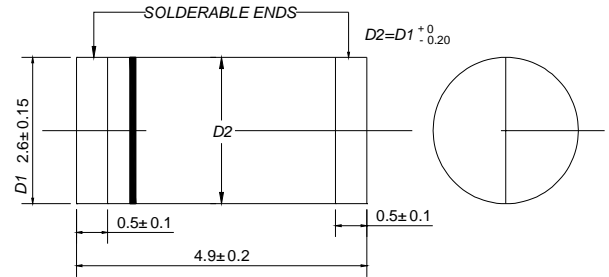
VOLTAGE RANGE: 50 --- 1600 V

CURRENT: 1.0 A

DO - 213AB

Features

- ✧ Plastic package has underwriters laboratories flammability classification 94V-0
- ✧ Glass passivated chip junction
- ✧ For surface mount applications
- ✧ High temperature metallurgically bonded construction
- ✧ Cavity-free glass passivated junction
- ✧ High temperature soldering guaranteed:450 °C/5 seconds at terminals.Complete device sub-mersible temperature of 265 °C for 10 seconds in solder bath



Dimensions in millimeters

Mechanical Data

- ✧ Case: JEDEC DO-213AB,molded plastic
- ✧ Polarity: Color band denotes cathode
- ✧ Weight: 0.0046 ounces, 0.116 grams
- ✧ Mounting position: Any

Maximum Ratings and Electrical Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase,half wave,60 Hz,resistive or inductive load. For capacitive load,derate current by 20%.

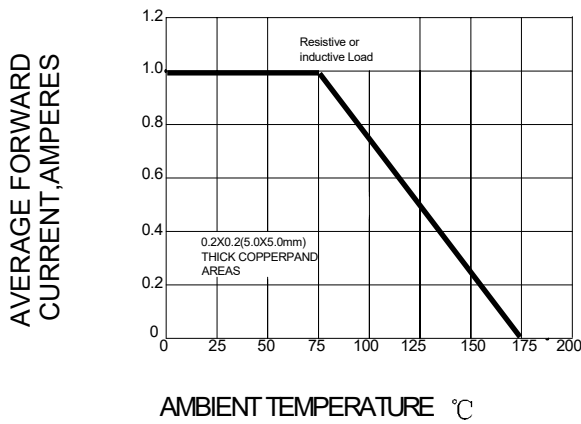
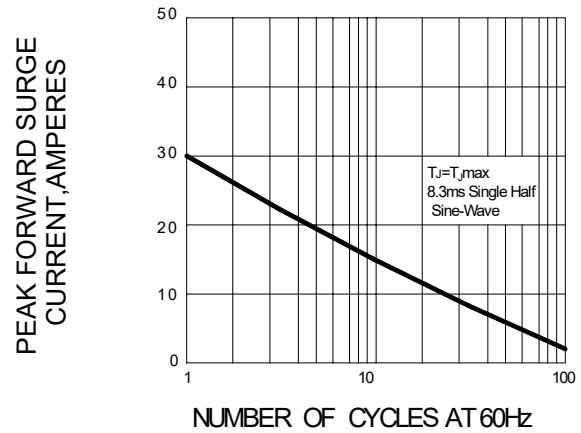
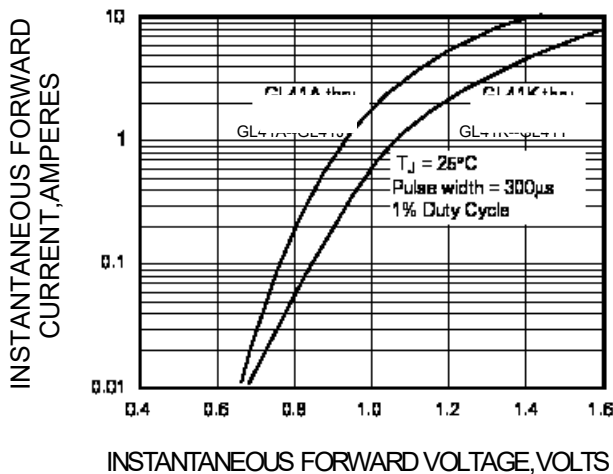
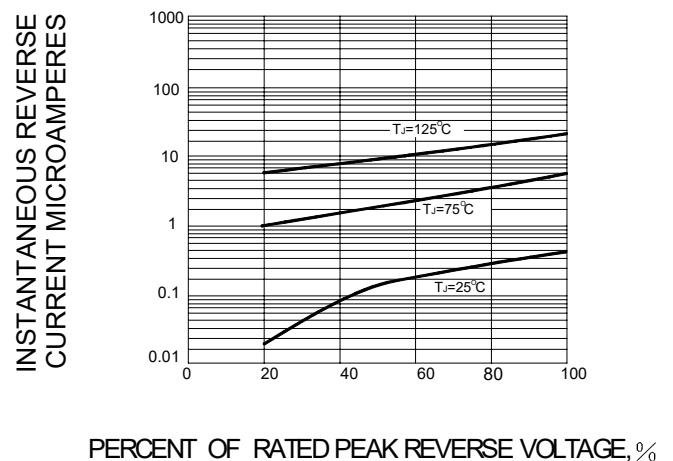
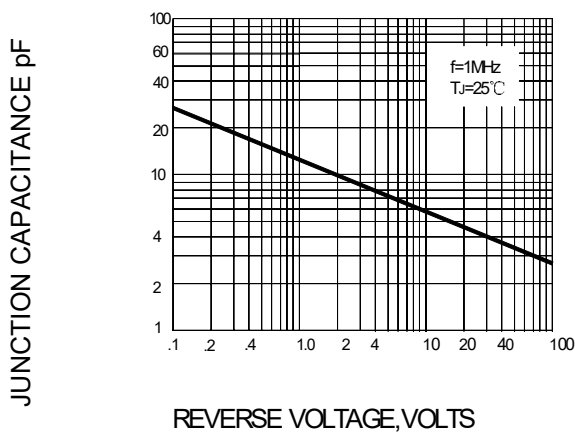
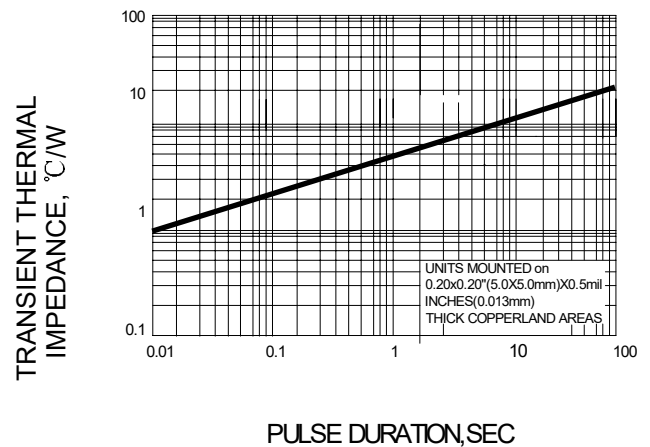
		GL 41A	GL 41B	GL 41D	GL 41G	GL 41J	GL 41K	GL 41M	GL 41T	GL 41Y	UNITS
Maximum recurrent peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	1300	1600	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	910	1120	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	1300	1600	V
Maximum average forward rectified current (see FIG.1)	$I_{(AV)}$	1.0									A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30									A
Maximum instantaneous forward voltage @1.0A	V_F	1.1					1.2				V
Maximum reverse current @ $T_A=25^{\circ}C$ at rated DC blocking voltage @ $T_A=125^{\circ}C$	I_R	5.0					50				μA
Typical junction capacitance (Note1)	C_j	8.0									pF
Typical thermal resistance (Note 2)	$R_{\theta JA}$	75									$^{\circ}C/W$
Operating junction temperature range	T_j	- 55 ---- +175									$^{\circ}C$
Storage temperature range	T_{STG}	- 55 ---- +175									$^{\circ}C$

NOTE: 1. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

2. Thermal resistance from junction to ambient, 0.24×0.24"(6.0×6.0mm) copper pads to each terminal.



Ratings AND Characteristic Curves

FIG.1 – FORWARD DERATING CURVE

FIG.2 PEAK FORWARD SURGE CURRENT

FIG.3 – TYPICAL FORWARD CHARACTERISTICS

FIG.4 – TYPICAL REVERSE CHARACTERISTICS

FIG.5-TYPICAL JUNCTION CAPACITANCE

FIG.6-TRANSIENT THERMAL IMPEDANCE


PACKAGE	SPQ/PCS	CARTON SPQ/PCS	CARTON SIZE/CM	CARTON GW/KG	CARTON NW/KG
DO-213AB	5000/REEL	80000	36.0X35.8X36.5	18.00	16.00